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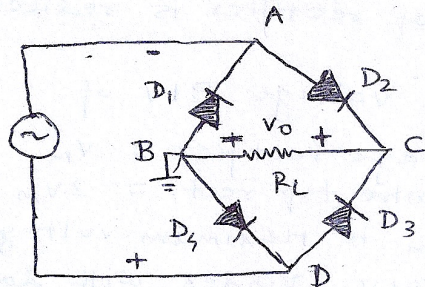
ASSIGNMENT-2

72

BASICS OF ELECTRONICS & COMM. ENGG.

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 SECTION: C-72
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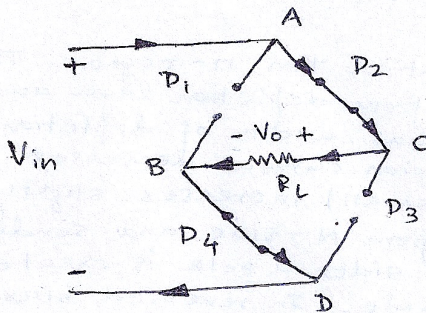
Q1.



Bridge rectifier circuit

Considering diodes D_1, D_2, D_3, D_4 to be ideal.
 \therefore Act as open branches when reverse biased.
 \therefore short branches when forward biased.

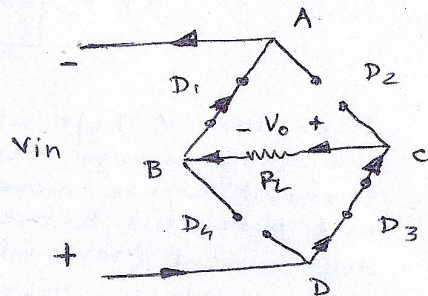
CASE 1



$V_A > V_D$

$\therefore D_2, D_4$ Forward Biased
 & D_1, D_3 Reversed Biased.
 \therefore current adopts path ACBD

CASE 2

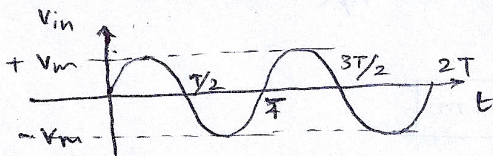


$V_D > V_A$

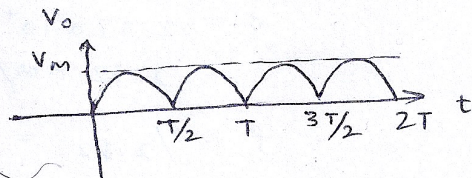
$\therefore D_2, D_4$ reversed Biased.
 & D_1, D_3 forward Biased
 \therefore current adopts path DCBA

\therefore During both cycles of Alternating input signal. Current across load is established in same direction: unidirectional pulsating current is obtained.

INPUT



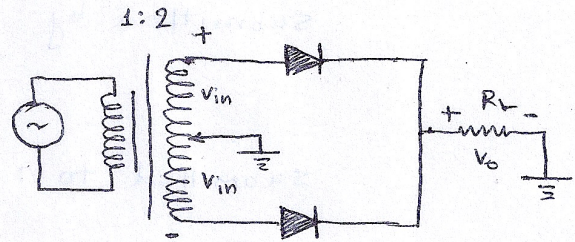
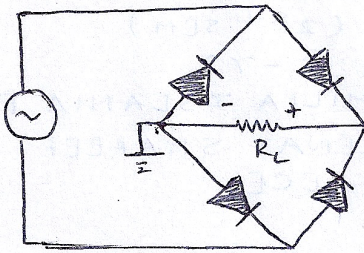
OUTPUT



Advantages of Bridge rectifier over full wave rectifier

Bridge rectifier

Centre Tap rectifier



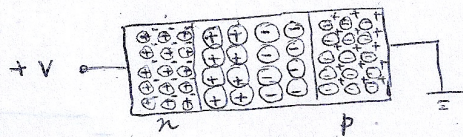
(1) In Bridge rectifier, need of transformer is removed. Hence size of rectifier is reduced.

(2) Peak inverse voltage PIV of
 Bridge rectifier = V_m
 centre tap rect. = $2V_m$

where V_m is Maximum voltage input

Due to less PIV, Diodes with lower breakdown voltages can be used.

Q2 (a) working of diode in reverse bias.



P region is kept at lower potential than n-region. This forces majority charge carriers away from depletion layer and as a result expose more ions and thus width of depletion layer ↑ and potential barrier also. Diffusion current decreases while drift current (remaining negligibly small) increases slightly. For each electron taken by battery from N-side and sending it for recombination with holes on P side, a hole is created on N side which drifts back to P-side. In reversed bias state diode acts as an open switch if ideal until its breakdown at higher reverse voltages. In practical diode however a reverse saturation current flows due to increased drift current.

(b) for intrinsic semiconductor, conductivity is given as $\sigma = nq(\mu_e + \mu_h)$ where, n : density of charge carriers
 q : charge of charge carriers
 μ_e : mobility of electrons
 μ_h : " " holes.

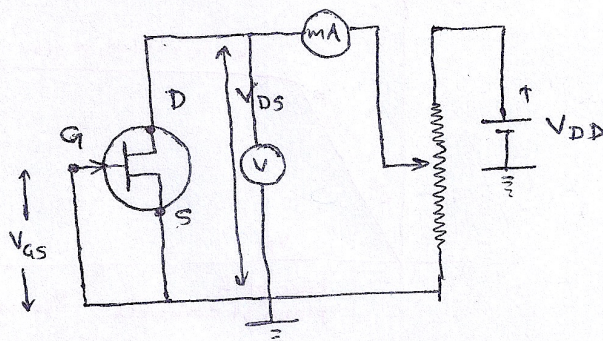
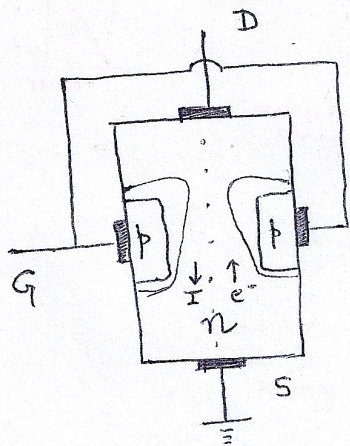
given, $n = 2.37 \times 10^{19} \text{ m}^{-3}$
 $\mu_e = 0.38 \text{ m}^2 \text{ V}^{-1} \text{ s}^{-1}$
 $\mu_h = 0.18 \text{ m}^2 \text{ V}^{-1} \text{ s}^{-1}$

$$\sigma = 2.37 \times 10^{19} \text{ m}^{-3} \times 1.6 \times 10^{-19} \text{ As} (0.38 + 0.18 \text{ m}^2 \text{ V}^{-1} \text{ s}^{-1})$$

$$= 2.12 \text{ A/Vm}$$

$$\rho = \frac{1}{2.12} = \boxed{0.471 \Omega \text{ m}}$$

Q3



Circuit for determining I/O characteristics

Drain characteristics with shorted gate ($V_{GS} = 0$)

CASE 1 $V_{DS} = 0$

There is no attracting path at drain \rightarrow no current flows inside channel is fully open.

$$\therefore I_D = 0$$

CASE 2

$V_{DS} < V_{pinch}$

Uptil knee pt $I_D \propto V_{DS}$.
Knee pt to pinch off $I_D = I_{DSS} \left[1 - \frac{V_{DS}}{V_P} \right]^2$

As V_{DS} is increased to a small value ($< V_P$), since D is at higher potⁿ & S is at lower potⁿ and there is conductive n channel in b/w having finite resistance / unit length. Hence, there is a gradual potⁿ drop from D to S across the channel. With decreasing potⁿ diffⁿ across p & n along D to S, the depletion layer is also thicker most towards drain gradually decreasing in width towards source. As V_{DS} is further increased, depletion layer thickens, consequently constricting the channel and thus increasing its resistance. Thus V_{DS} tries to increase I_D which will be decreased by increasing resistance of channel and will come to equilibrium when these opposing effects exactly cancel each other and I_D does not increase though V_{DS} is increased. This point is called pinch off when depletion layer physically start touching each other. V_{DS} at pinch off state is called pinch off voltage.

Initially when $V_{DS} < V_P$, the transistor acts as a constant resistor (Marked by ohmic region) upto knee pt arrives when resistance is no longer linear. From knee pt A to pinch off pt B, I_D increases with V_{DS} following a reverse square law.

CASE 3

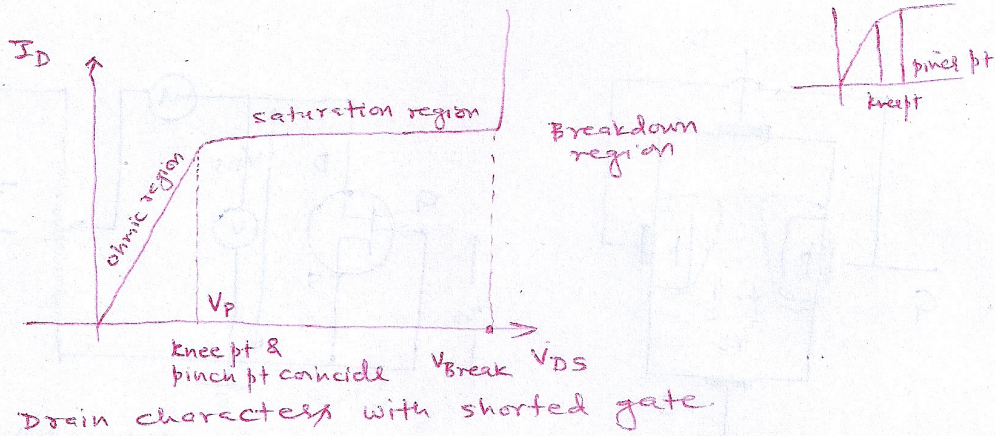
$V_{pinch} < V_{DS} < V_{breakdown}$

As per above description, I_D remains const. in this region. This const value of I_D at saturation is called I_{DSS} . However, JFET cannot remain a const. current device above a certain $V_{breakdown}$ after which avalanche effect come into play and its conductivity increases abruptly.

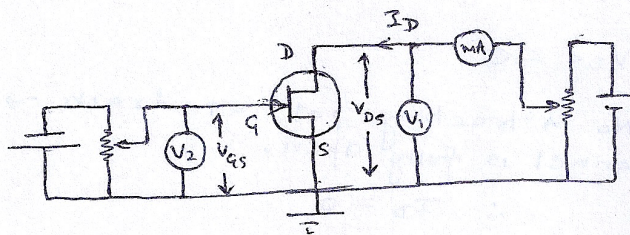
CASE 4

$V_{DS} > V_{breakdown}$

The channel breaks down, lot of charge carriers released and current increase very rapidly and JFET may be destroyed due to heat produced in this course.

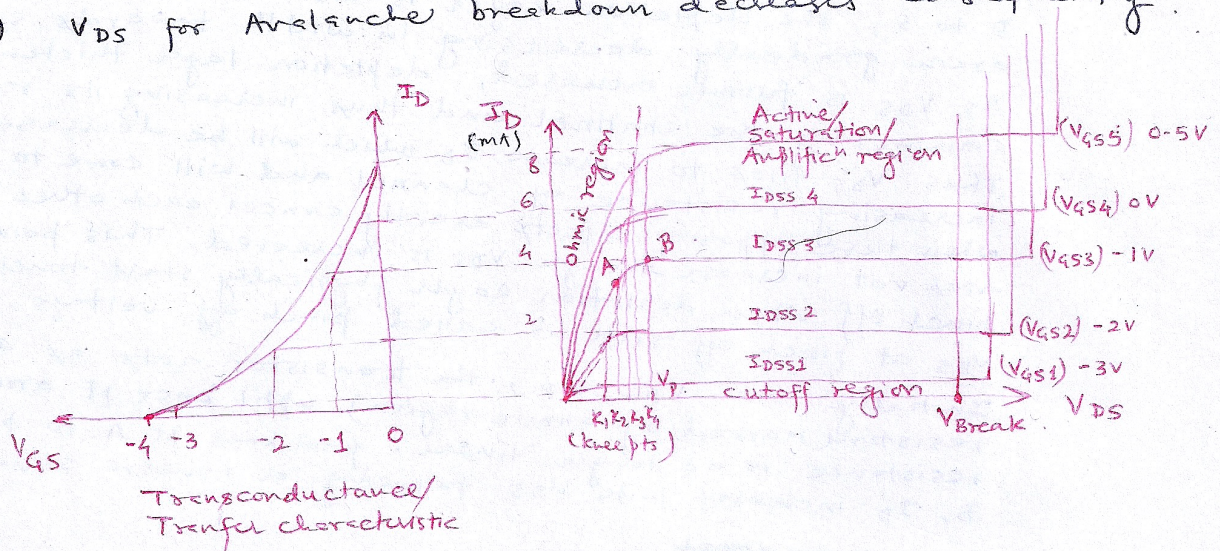


Drain characteristics with External Bias.



When negative gate bias voltage V_{GS} is increased:

- (i) saturation current decreases because pinch off is achieved earlier as -ive bias supports external V_{DS} .
- (ii) Gate channel junctions are reversed biased even when V_{DS} is zero i.e. depletion region penetrates into n channel even when there is no V_{DS} applied.
- (iii) V_{DS} for Avalanche breakdown decreases consequently.



By transfer characteristics it can be observed

- (i) drain current decreases with the increase in negative gate-source bias.
- (ii) Drain current, $I_D = I_{DSS}$ when $V_{GS} = 0$.
- (iii) Drain current, $I_D = 0$ when $V_{GS} = V_D$.

Advantages of BEFT over BJT

BJT

1. current controlled. Biasing current is required at base terminal for operation.
2. BJT offer smaller input impedances, meaning they draw more current from the power circuit feeding it, which can cause loading of circuit.
3. Larger in size. Not used in ICs.
- 4.
- 5.
- 6.

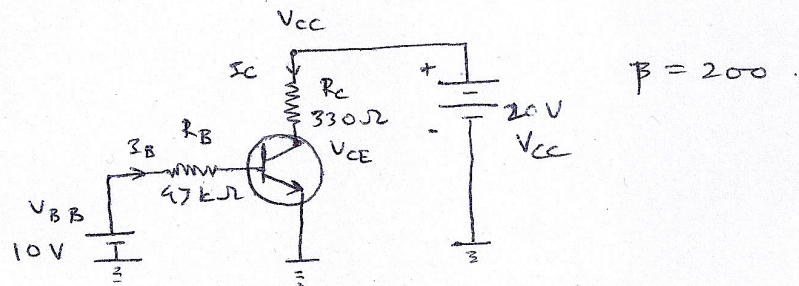
JEFT

voltage controlled. Biasing current not required for operation.

offer greater input impedance. Hence they draw very small current and does not load the power circuit feeding it.

smaller & easy to fabricate. Better thermal stability. Noise produced is lower. No offset voltage at zero drain current so forms an excellent signal chopper.

Q4.



This is a fixed bias configuration

assuming Si BJT

$$I_B = \frac{V_{BB} - V_{BE}}{R_B} = \frac{10 - 0.7}{47 \times 10^3}$$

$$\approx 0.198 \text{ mA}$$

$$I_{CQ} = \beta I_B = 200 \times 0.198 \text{ mA} \approx \boxed{39.6 \text{ mA}}$$

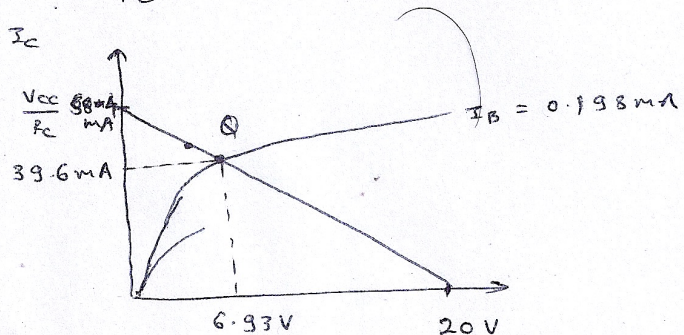
$$V_{CE} = V_{CC} - I_C R_C = 20 \text{ V} - 39.6 \text{ mA} \times 330 \Omega$$

$$= 20 - 13.07 \text{ V}$$

$$= \boxed{6.93 \text{ V}}$$

~~$$I_C = \frac{V_{CC} - V_{CE}}{R_C} = \frac{20 - 6.93}{330} = 39.6 \text{ mA}$$~~

$$I_{Cmax} = \frac{V_{CC} - V_{CE}}{R_C} = \frac{20 - 0}{330} = 60.6 \text{ mA}$$



Q (6.93V, 39.6mA)